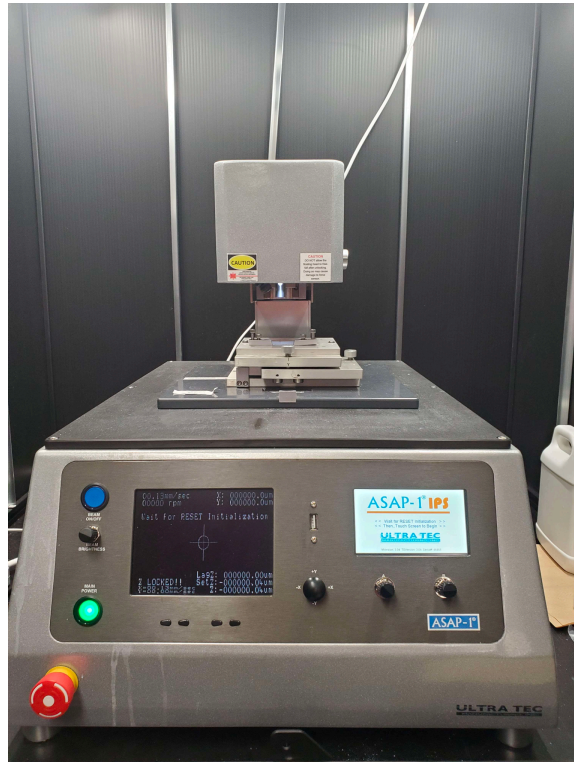


ASAP-1-IPS



Specifications

- Suits all sizes of die - package, wafer and board-level
- Full 100mm x 100mm stage area
- Always-On Real Time Video Monitor showing system and navigation parameters
- Touchscreen control with physical joystick & controls
- Ridgid Table Assembly and closed-loop, high-torque, motor control enhances the machining of tough and hard materials
- X, Y and Z axes all have deep sub-micron accuracy
- Accurately decaps, then thins substrate and polishes
- Patented Floating Head provides a true polishing action -- yields polishing quality & high survivability
- Intuitive menus provide a powerful, easy to use, system
- USB Flash Drive interface for preparation recipe storage
- Short set-up and process times
- Accurate die-tilt adjustment 'on the fly'
- Bench-top & Quiet in Operation